

119

Fig. 2

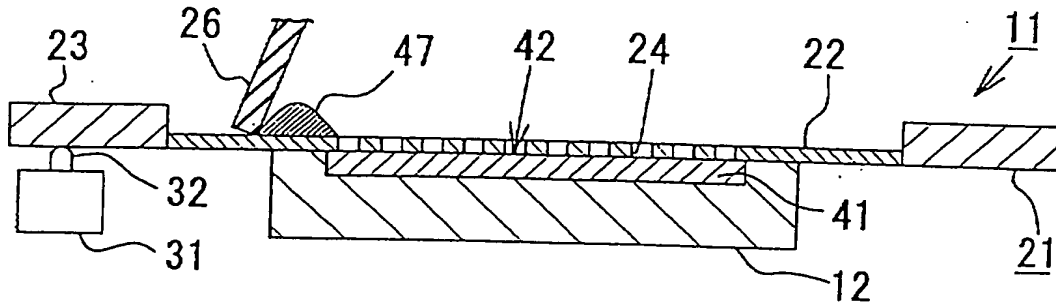


Fig. 3

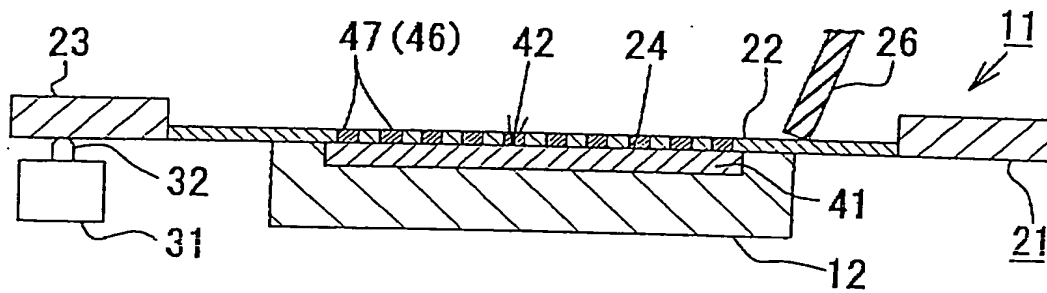


Fig. 4

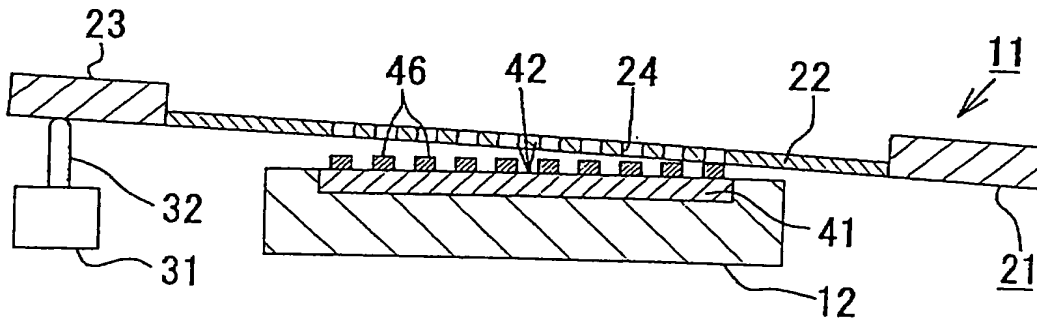


Fig. 5

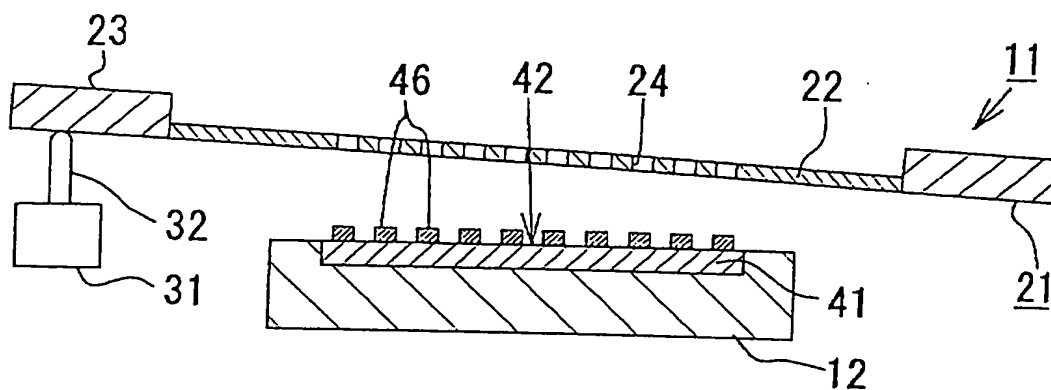


Fig. 6

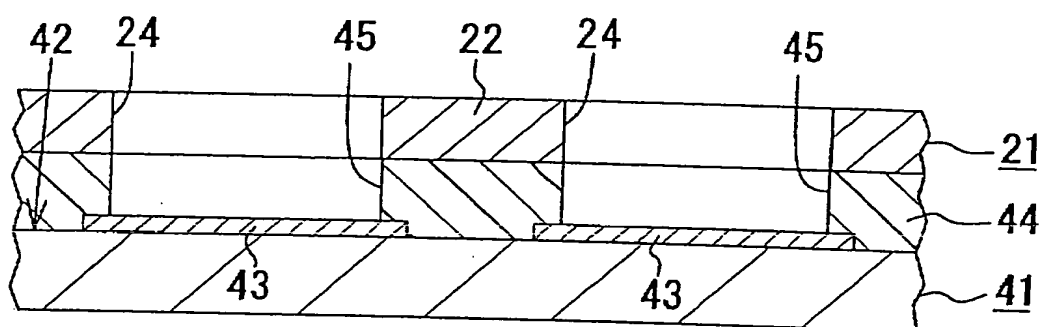
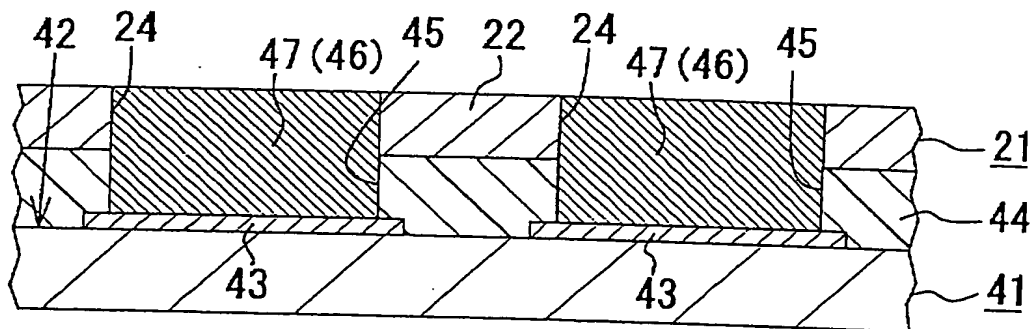


Fig. 7



A cross-sectional view of a semiconductor device. It shows a substrate 41 with a thin layer 44 on top. Two semiconductor elements 46 are mounted on the substrate. Each element 46 has a base layer 43 and a top layer 45. A contact pad 42 is located on the left side of the first element 46. The elements 46 are separated by a gap in the substrate 41.